DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby of My residence, post office address and I believe I am the original, first and so (if plural names are listed below) of the invention entitled MAGNETIC FIRst specification of which is attached here	citizenship are as stated below the inventor (if only one name subject matter which is cland the control of the	e is listed below) or an origina aimed and for which a patent is HOD AND DEVICE THE	s sought or	ı the	
was filed on September 30, 2 Application Number PCT/JP20	as United States Application Number or PCT International and was amended on (if applicable).				
I hereby state that I have reviewed and as amended by any amendment referred		the above identified specificat	ion, includ	ing the claims,	
I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56.					
I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.					
Prior Foreign Application(s)		Priority Date	Priority Claimed		
2002-291990	Japan	October 4, 2002	Yes	No	
(Number)	(Country) (PCT)	(Day/Month/Year Filed)	\boxtimes		
I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.					
(Application Number)		(Filing Date)			
I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.					
(Application Number)	(Filing Date)	(Status – patenteo	(Status - patented, pending, abandoned)		

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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